



RE900-03

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSOP I 20, 24 (0.50 mm)
- Hole diameter 1.00 mm
- Gerber data for manufacture of the soldering paste imprint will be provided free of charge on request
- Size 16.73 x 30.94 mm

Module-No.	Type	Pitch	Pin	Size (mm)
RE900-03	TSOP I	0.500 mm	20, 24	6.00 x 16.00